

**ABSTRACT OF THE DISCLOSURE**  
**SYSTEM FOR GRIPPING SOLDERING TOOL IN DIFFERENT WAYS**

This invention provides a system capable of melting solder and removing the melted solder from a substrate. The heating system includes a desoldering tool having at least two handles, a first handle and a second handle. This way, an operator may grip the first handle or the second handle depending on the operator's preference of gripping the desoldering tool. The first handle has a cavity adapted to releaseably receive a storage where the melted solder can be deposited and stored. The storage may have a divot adapted to receive a key from the first handle so that the storage may be orientated in a predetermined position relative to the cavity. The cavity in the first handle is exposed so that the storage can be readily inserted or replaced. This allows the operator to easily replace and maintain the desoldering tool without a significant downtime. The first handle is adapted to receive a heater cartridge having a transition section to couple the leading section and the electrical cartridge in a staggered manner. This configuration allows the leading section to have a shortened channel that is substantially straight and aligned with the passage formed within the first handle to minimize the resistant to flow of the melted solder through the channel which is then deposited into the storage.